

Wednesday, 25th September 2002	
11:00 - 13:00	SEMINAR Hot Bar Reflow Soldering. Heat-Seal Bonding. Anisotropic Conductive Film. Unitec Eapro part. I
13:00 - 14:00	Lunch
14:00 - 16:00	SEMINAR Hot Bar Reflow Soldering. Heat-Seal Bonding. Anisotropic Conductive Film. Unitec Eapro part.II
16:00 - 16:15	Coffee Break
16:15 - 16:30	Opening ceremony M. Jakubowska, L. Golonka, Jerzy Kurek, Jan Szmidt
16:30 - 18:00	PLENARY SESSION I (Chairmen: L. Golonka, Z. Drozd) <ul style="list-style-type: none"> • Invited paper 1: Semiconductor Devices – Silicon and Other Materials A.Jakubowski, L. Łukasiak, J. Szmidt • Invited paper 2: New Trends in High Density PCB Production and Assembly R.Kisiel • Invited paper 3: The Preparation and Properties of Thick Film Microstrip Lines on Substrates of Different Thickness for Low Cost Applications M. Jakubowska, C. Free, K. Pitt, Z. Tian
18:00 - 19:00	Supper
19:00 - 20:00	IMAPS members meeting
20:00	Grill party
Thursday, 26th September 2002	
8:00 - 9:00	Breakfast
9:00 - 10:30	PLENARY SESSION II (Chairmen: M. Ciez, R. Kisiel) <ul style="list-style-type: none"> • Invited paper 1: Simulated Thermal Cycling of Surface Components on FR4 Printed Wiring Boards Using Standard Tin Lead Solder K. Pitt, G. Goldspink • Invited paper 2: Effects of Dynamic Load of Layer Resistors Forecasted in Hybrid Microcircuit Designing Procedure. W. Kalita • Invited paper 3: The Influence of Silver Filler on Adhesive Joints in Microwave Applications J. Felba, K. Friedel, A. Guenther, A. Moœcicki, H. Schafer
10:30 - 11:00	Coffee break
11:00 - 13:00	Poster session I <ol style="list-style-type: none"> 1. MASKCAD – Computer System for Thick–Film Hybrid Circuit Layout Design - Practical Results F. Balik, A. Dziedzic, R. Dumański, R. Karkulowski 2. Structure and Residual Stress of Sputtered AlN Films G.Beensh-Marchwicka 3. Seebeck Effect of Some Thin Film Carbides G. Beensh-Marchwicka, E. Prociów 4. Modelling of Temperature Field Distribution in Thick-Film Sensor Structures G. Bład, Z. Hotra, D. Klepacki, J. Potencki 5. Interconnection for High Density PCB – Ways of Design Optimisation J. Borecki 6. Thermal Sensor with AC Heater Supplying J. Brzeziński, T.M. Berlicki 7. High Loaded Thick-Film Resistors on Steel Substrates. M. Cież, J. Gandurska, W. Grzesiak, J. Początek, K. Witek, W. Kalita, M. Węglarski, J. Koprowski 8. Microcomputer Equipped Sine- and Trapezoidal Output Wave DC/AC Inverters – Comparison of Features M.Cież, W. Grzesiak, J. Początek, T. Maj, W. Kalita, W.Sabat

	<p>9. Photoimageable Dielectric - Processing, Properties, Compatibility with Conventional and Photoimageable Thick Film Conductors B. Dziurdzia, S. Nowak, Z. Magoński, M. Cież,</p> <p>10. Training in Electronic Packaging Using Software Platforms D.V. Ene, C. Ionescu , V.Columbeanu</p> <p>11. Heating Elements on Insulated Steel Substrates J. Gandurska, I. Śnieżyńska, A. Marek, D. Szwagierczak, J. Kulawik, B. Gröger</p> <p>12. Electrode Materials of a Perovskite Structure on a Base of Sm, Dy and Co J. Gandurska, I. Śnieżyńska, A. Marek, D. Szwagierczak, J. Kulawik</p> <p>13. Modeling and Simulation of Resistors at High Frequency V. Golumbeanu, P. Svasta, M. Davidescu, I. Adjudeanu</p> <p>14. Modelling of Antenna Unit Total Impedance of RFID System Reader P. Jankowski – Miłłowicz, W.Kalita</p> <p>15. Suppression of Electromagnetic Interference in High Voltage Car Ignition Circuits by Means of Non- Inductive Bulk Ceramic Resistor E. Klimiec, W. Zaraska, A. Cichocki</p> <p>16. Temperature Characteristic of Film Carbon – Polymer Pressure Sensors A.M. Łukasik, M. Cież, K. Witek, W. Prochwicz</p> <p>17. Carbon – Polymer Layers As Activator in the Chemical Multilayer Metallization A.M. Łukasik, M. Cież, Z.Pruszowski</p> <p>18. UV Electroluminescence in Polymer Foil. A. Łukasik, M. Cież, W. Zaraska, P.Armatys</p> <p>19. Gluing and Encapsulation of SMD Resistors on Paper Phenolic Laminate A.M. Łukasik, K. Witek, M. Korpak</p>
13:00 - 14:00	Lunch
14:00 - 15:45	<p>Oral session supported by the Polish Committee for Scientific Research Oral presentation 10 min. Max (Chairmen: Andrzej Dziedzic, Jan Felba)</p> <p>1. Behaviour of High Value Resistors Under Static and Dynamic High Voltage Load M. Cież, W. Grzesiak, J. Początek, W. Kalita, J.Koprowski</p> <p>2. Testing of High Value Resistors' R vs.V Characteristics — Comparative Study M. Cież, W. Grzesiak, J. Początek, W. Zaraska, W. Kalita, J.Koprowski</p> <p>3. High Frequency Behaviour and Low Frequency Noise of LTCC Resistors A. Dziedzic, K.-H. Drüe, J. Kita, A. Kolek, P.Ptak</p> <p>4. 4.The New Thick-Film Paste Based on Cubic Boron Nitride M. Jakubowska, E. Zwierkowska, A. Młodziński, S. Achmatowicz, P. Gielisse, H.Niculescu</p> <p>5. Efficiency Optimization of Microcrystalline and Amorphous Silicon Solar Cells A. Kołodziej, P.Krewniak</p> <p>6. Optimization of Screen-Printed Ruthenium Dioxide Electrodes for pH Measurements I.Wyżkiewicz</p> <p>7. Modeling of SiGe-base Heterojunction Bipolar Transistors A. Zaręba, L. Łukasiak, A.Jakubowski</p> <p>8. Temperature and Stress Field in 3D Microvolume Resistors. T. Zawada, A. Dziedzic, L.J.Golonka</p>
15:45 - 16:15	Coffee break
16:15 - 18:00	<p>Poster session II</p> <p>1. Meniscographic Method of Investigation of Interfacial Surface Tension between Lead - Free Solders and Fluxes K. Bukat, J. Sitek, Z. Moser, W. Gąsior, R. Kisiel</p> <p>2. New Method of FPGA Circuits Design T. Maj</p>

	<p>3. Silver-Platinum Powder for Electronic Pastes A. Młodziak, M. Jakubowska, S. Osieczkin, E. Zwierkowska, S. Achmatowicz</p> <p>4. Current-Voltage Characteristics of Co-fired Cubic Boron Nitride H. Niculescu, P.J. Gielisse, J. P. Tremblay, S. Achmatowicz, M. Jakubowska, E.Zwierkowska</p> <p>5. Physical Bases of Electronics: Introduction of IT Elements. A. Patrin, W. Suslow, W.Ciepluch-Trojanek</p> <p>6. Ni-Cu-Sn-Pb Layers Manufactured by Meansof Chemical Reduction Method Z. Pruszowski, M. Cież, W. Grzesiak, K.Witek</p> <p>7. New Miniature Layer Fuses of Quick and Ultra-Quick Time-Current Characteristic J. Sulikowski, K. Widak, W.Gregoreczyk</p> <p>8. Modeling and Simulation of Capacitor Circuits at High Frequency P. Svasta, V. Golumbeanu, M. Davidescu, D.V.Ene</p> <p>9. Anisotropic Conductive Adhesives in FCOB and COG Technology Z. Szczepański, J. Kalenik, P. Zajączkowski</p> <p>10. Temperature Dependence of Electrical Conductivity for Relaxor Ceramics D. Szwagierczak, J. Kulawik, J. Gandurska, A. Marek, I. Śnieżyńska, B.Gröger</p> <p>11. Properties of Thick Film Ferroelectric Compositions. D. Szwagierczak, J. Kulawik, S. Nowak, A. Marek, J. Gandurska, I.Śnieżyńska</p> <p>12. Microcontroller Based Electronic Control Unit for High Vacuum Pumps Applications P. Svasta, C. Toma, Norocel-Dragos Codreanu</p> <p>13. Study of the Structure of the SnO₂ Thin Films Obtained by the RGTO Technique J. Uljanow, K.Waczyński</p> <p>14. Application of Artificial Intelligence to the Choice of Optimum Operation Parameters of a Thermal Sensor K.J.Urbański</p> <p>15. Doping Technology Using Silica Glasses - Investigation of the Emitter Layer of the Silicon Solar Cell K. Waczyński, K. Drabczyk, M. Lipiński, P.Panek</p> <p>16. Properties of Some Hybrid Microcircuit Components in Aspect of Temperature Measurements by Infrared Thermography T.Wałach</p> <p>17. Investigation of Solar Cells Under Varying Illumination P. Wójcik, T. Pisarkiewicz, T. Stapiński, M. Lipiński, P. Panek</p> <p>18. New Laser-Trim Configurations for High-Speed Algorithmic and Functional Trims M. Wroński</p> <p>19. Comparative Analysis of the Electrical Parameters of Self-made and Commercially Available RuO₂- based Thick Film Low-temperature Sensors D. Żak</p>
19:00	Gala dinner
Friday. 27th September 2002	
8:00 - 9:00	Breakfast
9:00 - 10:30	<p>PLENARY SESSION III (Chairmen: W. Kalita, M. Jakubowska)</p> <ul style="list-style-type: none"> • Invited paper 1: Problems of Cooperation between Research and Industry in Poland A.Jeleński • Invited paper 2: Microsystem Technology – New Challenges for Science and New Opportunities for Industry P.Grabiec
10:30 - 11:00	Coffee break
11:00 - 12:00	Didactic session.(Chairmen: R. Jezior, Z, Szczepanski)

	<ul style="list-style-type: none"> • Invited paper 1: Some Aspects of Packaging Education in the USA and Europe P. Svasta • Invited paper 2: Research and Education of Reliability in Electronic Interconnecting Technology Z. Drozd <p>Closing ceremony (Chairmen: M. Jakubowska, L. Golonka)</p>
12:00 - 13:00	Assemblon seminar
13:00 - 14:00	Lunch